

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ018N04LS6	**Issued**	11. April 2021
MA#	MA005350239		
Package	PG-TSDSON-8-34	**Weight***	35.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.723	2.01	2.01	20104	20104
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		100	
	non noble metal	zinc	7440-66-6	0.014	0.04		401	
	non noble metal	iron	7439-89-6	0.288	0.80		8014	
	non noble metal	copper	7440-50-8	11.710	32.54	33.39	325419	333934
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	766	766
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		970	
	plastics	epoxy resin	-	1.798	5.00		49953	
	inorganic material	silicondioxide	60676-86-0	15.620	43.40	48.50	434058	484981
leadfinish	non noble metal	tin	7440-31-5	0.395	1.10	1.10	10984	10984
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	565	565
solder	non noble metal	tin	7440-31-5	0.020	0.05		544	
	noble metal	silver	7440-22-4	0.024	0.07		680	
	non noble metal	lead	7439-92-1	0.935	2.60	2.72	25989	27213
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			36	
	non noble metal	iron	7439-89-6	0.004	0.01		119	
	non noble metal	copper	7440-50-8	4.267	11.86	11.87	118585	118740
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.097	0.27	0.27	2709	2713
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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